

ABSTRACT

The present invention provides a positive photosensitive composition comprising (A) an alkali-soluble resin, (B) a naphthoquinone diazide compound, (C) a solvent and (D) a metal chelate compound, which is characterized in that the (D) metal chelate compound has a structure represented by the following Formula (1) and the content of the (D) metal chelate compound is 0.1 to 5 parts by weight compared to 100 parts by weight of the (A) alkali-soluble resin.

The positive photosensitive composition of the present invention has characteristic features such as high heat resistance and high transparency as well as excellent adhesion in development and wet-heat resistance.